L Number	Hits	Search Text	DB	Time stamp
1	3	360/760	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 17:50
2	3756	361/760	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 18:39
3	2109	438/108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 18:58
4	998	438/109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:19
5	14	4971930.pn. or 5530282.pn. or 6512219.pn. or 5440231.pn. or 6114770.pn. or 6353265.pn. or 6369595.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:21
-	44	(dual or double) near (semiconductor or die or chip or IC) with lead	USPAT	2004/08/17 17:38
-	4	(dual or double) near (semiconductor or die or chip or IC) with lead and ground	USPAT	2004/08/17 17:48
-	70	(dual or double or both) near (semiconductor or die or chip or IC) with lead and ground	USPAT	2004/08/17 18:11
-	126	(semiconductor or die or chip or IC) with lead and ground with (die near (pad or paddle))	USPAT	2004/08/17 22:13
-	133	(semiconductor or die or chip or IC) and lead and ground with (die near (pad or paddle))	USPAT	2004/08/17 23:06
-	194	(semiconductor or die or chip or IC) and lead and ground same (die near (pad or paddle))	USPAT	2004/08/17 22:49
-	61	((semiconductor or die or chip or IC) and lead and ground same (die near (pad or paddle))) not ((semiconductor or die or chip or IC) and lead and ground with (die near (pad or paddle)))	USPAT	2004/08/17 22:16
-	2806	(semiconductor or die or chip or IC) and lead and ground and MOSFET	USPAT	2004/08/17 22:35
-	664	(semiconductor or die or chip or IC) and lead and ground with MOSFET	USPAT	2004/08/17 22:35
-	1	"5291054".PN.	USPAT	2004/08/17 23:05
-	1	"5365087".PN.	USPAT	2004/08/17 23:06
-	1	"5466962".PN.	USPAT	2004/08/17 23:06
-	7	"5291054"	USPAT	2004/08/18 11:30
-	7	5814881.pn. or 5719436.pn. or 6069025.pn. or 4763188.pn. or 5815372.pn. or 6388333.pn. or 6441495.pn.	USPAT	2004/08/18 11:40
-	4	"6118184" and ground	USPAT	2004/08/18 11:41
-	21	"6118184"	USPAT	2004/08/18 11:41
-	1231	controlled with collapse with chip	USPAT	2004/08/19 20:29
-	1219	controlled near collapse with chip	USPAT	2004/08/19 20:29
-	1097	controlled near collapse near chip	USPAT	2004/08/19 20:42
-	977	controlled near collapse near chip near connection	USPAT	2004/08/19 21:48
-	968	438/614	USPAT	2004/08/19 21:48
-	968	438/614	USPAT	2004/08/19 21:49
-	480	(438/614).CCLS.	USPAT	2004/08/19 21:57
-	2	6133637.pn. or 5903049.pn.	USPAT	2004/08/20 13:19
-	3211	257/666	USPAT	2004/08/20 13:19
-	293	257/666 and ground with (pad or paddle or mount$3 near structure)	USPAT	2004/08/20 14:31

-	283	(257/666 and ground with (pad or paddle or mount$3 near structure)) and wir$3	USPAT	2004/08/20 13:41
-	35	(semicodncutor or die or chip or IC) and lead and wir$3 and bottom near (pad or terminal or contact or electrode) with (die near pad or paddle or mount$3 near structure)	USPAT	2004/08/20 14:46
-	1708	(semicodncutor or die or chip or IC) and lead and wir$3 and (electric$4 or ground) with (die near pad or paddle or mount$3 near structure)	USPAT	2004/08/20 14:46
-	9	(semicodncutor or die or chip or IC) and lead and wir$3 and (electric$4 or ground) with (die near pad or paddle or mount$3 near structure) with bottom near (pad or terminal or contact or electrode)	USPAT	2004/08/20 14:48
-	591	(semicodncutor or die or chip or IC) and lead and wir$3 and (electric$4 near connection or ground) with (die near pad or paddle or mount$3 near structure)	USPAT	2004/08/20 14:49
-	0	(semicodncutor or die or chip or IC) and lead and wir$3 and (electric$4 near connection or ground) with (die near pad or paddle or mount$3 near structure) with (thru) with adhesive	USPAT	2004/08/20 14:49
-	16	(semicodncutor or die or chip or IC) and lead and wir$3 and (electric$4 near connection or ground) with (die near pad or paddle or mount$3 near structure) with adhesive	USPAT	2004/08/20 14:56
-	161	(semicodncutor or die or chip or IC) and lead and wir$3 and (electric$4 near connection or ground) with (die near pad or paddle or mount$3 near structure) with between with (semicodncutor or die or chip or IC)	USPAT	2004/08/20 17:31
-	54	(semicodncutor or die or chip or IC) and lead and wir$3 and (die near pad or paddle or mount$3 near structure) with (MOSFET or power) near (semicodncutor or die or chip or IC)	USPAT	2004/08/20 17:43
-	221	(semicodncutor or die or chip or IC) and wir$3 and lead with (MOSFET or power) near (semicodncutor or die or chip or IC)	USPAT	2004/08/22 20:18
-	9	(semicodncutor or die or chip or IC) and wir$3 and lead with (MOSFET or power) near (semicodncutor or die or chip or IC) and adhesive with (ground or electric$5 near connection)	USPAT	2004/08/22 20:21
-	9	(semicodncutor or die or chip or IC) and wir$3 and lead with (MOSFET or power) near (semicodncutor or die or chip or IC) and (adhesive or glue) with (ground or electric$5 near connection)	USPAT	2004/08/22 20:22
-	1062	(semicodncutor or die or chip or IC) and wir$3 and lead and (adhesive or glue) with (ground or electric$5 near connection)	USPAT	2004/08/22 20:22
-	190	(semicodncutor or die or chip or IC) and wir$3 and lead with (adhesive or glue) with (ground or electric$5 near connection)	USPAT	2004/08/22 20:22
-	19292	5545922.pn. adhesive with conductive	USPAT	2004/08/23 00:42
-	0	5545922.pn. and adhesive with conductive	USPAT	2004/08/23 00:40
-	0	5545922.pn. and adhesive with ("Ag" or silver)	USPAT	2004/08/23 00:40
-	26	"5545922"	USPAT	2004/08/23 00:41
-	28668	"5545922" adhesive with (conduct$3 or "Ag" or silver)	USPAT	2004/08/23 00:42
-	3	"5545922" and adhesive with (conduct$3 or "Ag" or silver)	USPAT	2004/08/23 00:43

-	8	"6072243" and adhesive with (conduct$3 or "Ag" or silver)	USPAT	2004/08/23 00:48
-	924	257/666 and adhesive with (conduct$3 or "Ag" or silver)	USPAT	2004/08/23 00:53
-	1	"3627901".PN.	USPAT	2004/08/23 00:49
-	1	"3678385".PN.	USPAT	2004/08/23 00:49
-	1	"3930114".PN.	USPAT	2004/08/23 00:49
-	1	"4089575".PN.	USPAT	2004/08/23 00:49
-	1	"4506238".PN.	USPAT	2004/08/23 00:50
-	28	(257/666 and adhesive with (conduct$3 or "Ag" or silver)) and (dual or double) near (semiconductor or die or chip or IC)	USPAT	2004/08/23 00:53
-	7	"5291054"	USPAT	2004/08/23 03:02
-	0	5291054.pn. and mosfet	USPAT	2004/08/23 03:13
-	3211	257/666	USPAT	2004/08/23 03:26
-	610	257/670	USPAT	2004/08/23 03:15
-	785	257/670	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 03:15
-	2104	257/666	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 03:47
-	9	invar with molding	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 03:48
-	10	invar with molding	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/23 03:48
-	11	invar with molding	USPAT	2004/08/23 03:49
-	0	invar with (molding near resin or encapsulating)	USPAT	2004/08/23 03:49
-	14	invar with (molding near resin or encapsulat$3)	USPAT	2004/08/23 03:55
-	0	invar with (molding near resin or encapsulat$3) with adhesi$2	USPAT	2004/08/23 03:56
-	0	invar with (molding near resin or encapsulat$3) with adhesion	USPAT	2004/08/23 03:56
-	0	invar with (molding near resin or encapsulat$3) with adhesive	USPAT	2004/08/23 03:56
-	0	invar with (molding near resin or encapsulat$3) with adhes$3	USPAT	2004/08/23 03:56
-	1	invar with (molding near resin or encapsulat$3) same adhes$3	USPAT	2004/08/23 04:33
-	0	"20020180035"	USPAT	2004/08/23 04:33
-	1	"20020180035"	USPAT; US-PGPUB	2004/08/23 05:32
-	18	"5949135"	USPAT; US-PGPUB	2004/08/23 05:32
-	1614	(semiconductor or die or chip or IC) same (mold$3 or encapsulat$3) with recess	USPAT	2004/08/23 09:52
-	725	((semiconductor or die or chip or IC) same (mold$3 or encapsulat$3) with recess) and lead	USPAT	2004/08/23 09:53
-	1	"4996587".PN.	USPAT	2004/08/23 11:55
-	1	"5394010".PN.	USPAT	2004/08/23 11:55
-	1	"5475259".PN.	USPAT	2004/08/23 12:02
-	1	"6021563".PN.	USPAT	2004/08/23 12:03
-	1	"6146919".PN.	USPAT	2004/08/23 12:03
-	1	"6320251".PN.	USPAT	2004/08/23 12:03
-	1	"6424031".PN.	USPAT	2004/08/23 12:04
-	1	"6424031".PN.	USPAT	2004/08/23 12:06
-	1	"6320251".PN.	USPAT	2004/08/23 12:06
-	2262	(semiconductor or die or chip or IC) and lead with recess	USPAT	2004/08/30 12:53
-	1022	(semiconductor or die or chip or IC) same lead with recess	USPAT	2004/08/30 12:55

-	142	(semiconductor or die or chip or IC) same lead with recess same recess with (mold$3 or encapsulat$3)	USPAT	2004/08/30 16:43
-	880	((semiconductor or die or chip or IC) same lead with recess) not ((semiconductor or die or chip or IC) same lead with recess same recess with (mold$3 or encapsulat$3))	USPAT	2004/08/30 13:57
-	1240	((semiconductor or die or chip or IC) and lead with recess) not ((semiconductor or die or chip or IC) same lead with recess)	USPAT	2004/08/30 14:25
-	7	"5403785"	USPAT	2004/08/30 14:25
-	1	"4413404".PN.	USPAT	2004/08/30 14:50
-	1	"4776509".PN.	USPAT	2004/08/30 14:50
-	1	"4800178".PN.	USPAT	2004/08/30 14:50
-	1	"4994412".PN.	USPAT	2004/08/30 14:56
-	1	"5001545".PN.	USPAT	2004/08/30 14:58
-	1	"5040293".PN.	USPAT	2004/08/30 14:58
-	1	"5157475".PN.	USPAT	2004/08/30 14:58
-	1	"5157480".PN.	USPAT	2004/08/30 14:59
-	1	"5367196".PN.	USPAT	2004/08/30 14:59
-	1	"5454905".PN.	USPAT	2004/08/30 14:59
-	1	"5494207".PN.	USPAT	2004/08/30 15:00
-	1	"5508556".PN.	USPAT	2004/08/30 15:00
-	1	"5521429".PN.	USPAT	2004/08/30 15:00
-	1	"5596231".PN.	USPAT	2004/08/30 15:00
-	1	"5623123".PN.	USPAT	2004/08/30 15:01
-	1	"5656550".PN.	USPAT	2004/08/30 15:01
-	1	"5741729".PN.	USPAT	2004/08/30 15:02
-	1	"5844315".PN.	USPAT	2004/08/30 15:02
-	1	"5854511".PN.	USPAT	2004/08/30 15:03
-	1	"5866948".PN.	USPAT	2004/08/30 15:03
-	1	"5981314".PN.	USPAT	2004/08/30 15:03
-	1	"5990545".PN.	USPAT	2004/08/30 15:03
-	1	"6013946".PN.	USPAT	2004/08/30 15:04
-	1	"6060774".PN.	USPAT	2004/08/30 15:04
-	1	"6060778".PN.	USPAT	2004/08/30 15:04
-	1	"6093960".PN.	USPAT	2004/08/30 15:05
-	1	"6130473".PN.	USPAT	2004/08/30 15:05
-	1	"6060774".PN.	USPAT	2004/08/30 15:06
-	1	"6060778".PN.	USPAT	2004/08/30 15:08
-	1	"6093960".PN.	USPAT	2004/08/30 15:09
-	1	"6130473".PN.	USPAT	2004/08/30 15:54
-	1	"6133070".PN.	USPAT	2004/08/30 15:54
-	1	"6177288".PN.	USPAT	2004/08/30 16:00
-	1	"6188130".PN.	USPAT	2004/08/30 16:00
-	1	"6201292".PN.	USPAT	2004/08/30 16:00
-	1	"6215179".PN.	USPAT	2004/08/30 16:32
-	1	"4774635".PN.	USPAT	2004/08/30 16:36
-	1	"5006917".PN.	USPAT	2004/08/30 16:36
-	1	"5635755".PN.	USPAT	2004/08/30 16:36
-	1	"5663594".PN.	USPAT	2004/08/30 16:38
-	1	"5834831".PN.	USPAT	2004/08/30 16:38
-	1	"5977613".PN.	USPAT	2004/08/30 16:39
-	0	(semiconductor or die or chip or IC) same lead with glove same recess with (mold$3 or encapsulat$3)	USPAT	2004/08/30 16:42
-	0	(semiconductor or die or chip or IC) same lead with gloove same recess with (mold$3 or encapsulat$3)	USPAT	2004/08/30 16:42
-	1	(semiconductor or die or chip or IC) same lead with indent$5 same recess with (mold$3 or encapsulat$3)	USPAT	2004/08/30 16:47
-	18	(semiconductor or die or chip or IC) same lead with indent$5 same indent$5 with (mold$3 or encapsulat$3)	USPAT	2004/08/30 16:53
-	24	(semiconductor or die or chip or IC) and lead with indent$5 same indent$5 with (mold$3 or encapsulat$3)	USPAT	2004/08/30 17:11
-	250	(semiconductor or die or chip or IC) and lead with (indent$5 or groove) same (indent$5 or groove) with (mold$3 or encapsulat$3)	USPAT	2004/08/30 17:11

-	223	(semiconductor or die or chip or IC) and lead with (indent$5 or groove) with (indent$5 or groove) with (mold$3 or encapsulat$3)	USPAT	2004/08/30 17:12
-	1	"5294827".PN.	USPAT	2004/08/30 17:44
-	1	"5521429".PN.	USPAT	2004/08/30 17:44
-	1	"5841187".PN.	USPAT	2004/08/30 17:45
-	1	"5844307".PN.	USPAT	2004/08/30 17:45
-	1	"5900676".PN.	USPAT	2004/08/30 17:46
-	1	"5973388".PN.	USPAT	2004/08/30 17:46
-	1	"5977613".PN.	USPAT	2004/08/30 17:48
-	787	257/670	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 16:46
-	268	257/671	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 16:53
-	3250	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 17:25
-	2301	257/676	USPAT	2004/08/31 16:55
-	949	257/676 not 257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 17:45
-	2736	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 17:50
-	2182	257/686	USPAT	2004/08/31 17:28
-	554	257/686 not 257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 18:39
-	1182	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 18:04
-	295	257/689	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 18:07
-	2126	257/713	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 18:08
-	1804	257/713	USPAT	2004/08/31 18:42
-	322	257/713 not 257/713	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 19:04
-	2504	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 19:08
-	2113	257/777	USPAT	2004/08/31 18:45

–	391	257/777 not 257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 19:28
–	4071	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 19:33
–	3534	257/778	USPAT	2004/08/31 19:11
–	537	257/778 not 257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 19:29
–	1664	257/783	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 19:58
–	4662	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 17:49